3D Printing and Power Supply on Chip (PwrSoC) / Power Supply in Package (PSiP) vs. Discrete Designs

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Factors affecting this topic

- Reliability
- Cost
- Size
- Thermal management
- Manufacturability
- Power handling capability
- Efficiency
Session format

• Poll of audience opinion on Integration vs Discrete

• Introduction of the topic by speakers

• Audience questions & discussion
Question

• What is the most significant challenge in integration of components in power supplies?

− Cost
− Reliability
− Thermal
− Power handling capability
− Manufacturability

Audience response: Cost and Thermal